Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Hui-Min Wu	10/09/2009
Bang-Chiang Lan	10/09/2009
Ming-I Wang	10/09/2009
Tzung-I Su	10/09/2009
Chien-Hsin Huang	10/09/2009
Chao-An Su	10/09/2009
Tzung-Han Tan	10/09/2009
Min Chen	10/09/2009
Meng-Jia Lin	10/09/2009

RECEIVING PARTY DATA

Name:	UNITED MICROELECTRONICS CORP.
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park
City:	Hsin-Chu City
State/Country:	TAIWAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12577734

CORRESPONDENCE DATA

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PATENT 500986437 **REEL: 023359 FRAME: 0901**

NAME OF SUBMITTER:	WINSTON HSU
Total Attachments: 3 source=712557#page1.tif source=712557#page2.tif source=712557#page3.tif	

PATENT REEL: 023359 FRAME: 0902

ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

ASSIGNOR(S) (Inventors):

Name:	Hui-Min Wu	Nationality:	TWN
Name:	Bang-Chiang Lan	Nationality:	TWN
Name:	Ming-I Wang	Nationality:	TWN
Name:	Tzung-I Su	Nationality:	TWN
Name:	Chien-Hsin Huang	Nationality:	TWN
Name:	Chao-An Su	Nationality:	TWN
Name:	Tzung-Han Tan	Nationality:	TWN
Name:	Min Chen	Nationality:	TWN
Name:	Meng-Jia Lin	Nationality:	TWN

Hereby sells, assigns and transfers to

ASSIGNEE(S):

Assignment, Page 1 of 3

F#NPO-P0002E-US1 DSB0-098U024388 Name: UNITED MICROELECTRONICS CORP. Address: No.3, Li-Hsin Road 2, Science-Based Industrial Park, Hsin-Chu City 300, Taiwan, R.O.C.

and the successors and assignees of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

"Semiconductor Structure"

Which is for	nd in:
(a) <u>+</u>	U.S. patent application executed on even date
(b)	U.S. patent application executed on
(c)	U.S. application serial no
(d)	patent no issued

and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal this > 0.9.0 ct. 0 9 (Date of signing). (清條明人務必義署上列目期:)

(Type name of inventor)	Signature of INVENTOR
Hui-Min Wu	Hui-Min Wu
Bang-Chiang Lan	Bang-Chiang Lan
Ming-I Wang	Wong, Ming- N
Tzung-I Su	Tzung-I Su.
Chien-Hsin Huang	Chion-Hsin Huang
Chao-An Su	Chao An Su
Tzung-Han Tan	Trung Han Jan
Min Chen	Min Then
Meng-Jia Lin	Meng Jia Lin
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PATENT REEL: 023359 FRAME: 0905